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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Document No.: 60188-649

In re Application of

SHIRAKASHI, et al.

Application No.: 10/665,015

Filed: September 22, 2003

Customer Number: 20277

Confirmation Number: 5843

Group Art Unit: 3723

Examiner: McDonald, Shantese L.

For: METHOD FOR POLISHING SEMICONDUCTOR WAFER AND POLISHING PAD FOR THE SAME

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith is an Amendment in the above-identified application.

- ☒ No additional fee is required.
☐ Applicant is entitled to small entity status under 37 CFR 1.27
☐ Also attached:

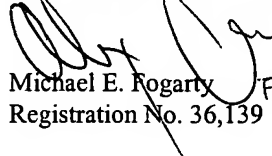
The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	6	20	0	\$50.00 =	\$0.00
Independent Claims	2	3	0	\$200.00 =	\$0.00
Multiple claims newly presented					\$0.00
Fee for extension of time					\$0.00
					\$0.00
Total of Above Calculations					\$0.00

- ☐ Please charge my Deposit Account No. 500417 in the amount of \$0.00. An additional copy of this transmittal sheet is submitted herewith.
- ☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

McDERMOTT WILL & EMERY-LLP


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Date: December 22, 2004

Please recognize our Customer No. 20277 as our
correspondence address.



Pocket No.: 60188-649

PATENT

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In Application of

Eigo SHIRAKASHI, et al.

Application No.: 10/665,015

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: Customer Number: 20277

: Confirmation Number: 5843

: Group Art Unit: 3723

: Examiner: MCDONALD, SHANTESE L.

For: METHOD FOR POLISHING SEMICONDUCTOR WAFER AND POLISHING PAD FOR
THE SAME

AMENDMENT UNDER 37 C.F.R. §1.111

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated September 24, 2004, having a shortened statutory period for response set to expire December 24, 2004, please amend the above-identified application as follows: